

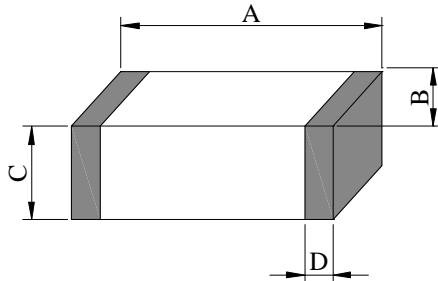
SPECIFICATION FOR APPROVAL

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PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MH1005□□□□L□-□□□
		ABC'S ITEM NO.	

I . CONFIGURATION & DIMENSIONS :



- A : 1.00±0.10 m/m
- B : 0.50±0.10 m/m
- C : 0.50±0.10 m/m
- D : 0.23±0.10 m/m

II . SCHEMATIC DIAGRAM :



III . FEATURES :

- a . Monolithic structure ensuring high performance and reliability.
- b . High frequency applications up to 6GHz.
- c . Terminal : Ag/Cu/Ni/Sn
- d . Remark : Products comply with RoHS' requirements

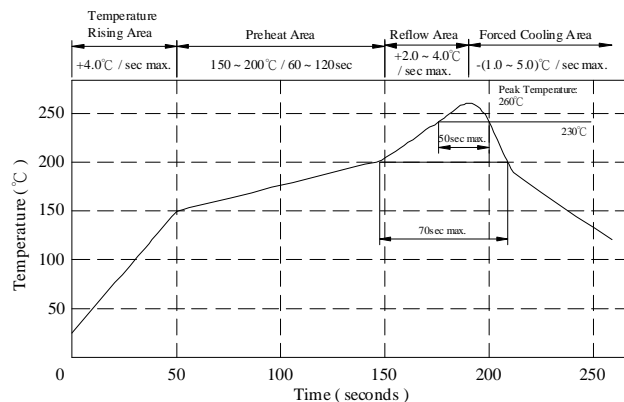
IV . APPLICATIONS :

- a . RF modules for telecommunication systems including GSM, PCS, DECT, WLAN, Bluetooth, etc.

V . GENERAL SPECIFICATION :

- a . Storage temp. : -55°C ---- +125°C
- b . Operating temp. : -55°C ---- +125°C
- c . Solderability : Preheat 150°C . 60 sec
 Solder : H63A
 Solder temp. : 230±5°C
 Flux : Rosin
 Dip time : 4±1 sec

Peak Temp : 260°C max.
 Max time above 230°C : 50sec max.
 Max time above 200°C : 70sec max.



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VI . ELECTRICAL CHARACTERISITCS :

DWG No.	Inductance (nH)	Q min	L / Q Test Freq. (MHz)	SRF (MHz) nom	RDC (Ω) max	IDC (mA) max
MH10051N0DL□-□□□	1.0 ±0.3	8	100	>15000	0.12	300
MH10051N2DL□-□□□	1.2 ±0.3	8	100	>15000	0.12	300
MH10051N5DL□-□□□	1.5 ±0.3	8	100	>15000	0.13	300
MH10051N8DL□-□□□	1.8 ±0.3	8	100	14000	0.14	300
MH10052N2DL□-□□□	2.2 ±0.3	8	100	12000	0.16	300
MH10052N7DL□-□□□	2.7 ±0.3	8	100	9500	0.17	300
MH10053N3DL□-□□□	3.3 ±0.3	8	100	8500	0.19	300
MH10053N9DL□-□□□	3.9 ±0.3	8	100	7000	0.22	300
MH10054N7DL□-□□□	4.7 ±0.3	8	100	6000	0.24	300
MH10055N6DL□-□□□	5.6 ±0.3	8	100	5400	0.27	300
MH10056N8JL□-□□□	6.8 ±5%	8	100	5000	0.32	250
MH10058N2JL□-□□□	8.2 ±5%	8	100	4600	0.40	250
MH100510NJL□-□□□	10.0 ±5%	8	100	3700	0.45	250
MH100512NJL□-□□□	12.0 ±5%	8	100	3200	0.50	250
MH100515NJL□-□□□	15.0 ±5%	8	100	3100	0.60	250
MH100518NJL□-□□□	18.0 ±5%	8	100	2900	0.65	200
MH100522NJL□-□□□	22.0 ±5%	8	100	2100	0.80	200
MH100527NJL□-□□□	27.0 ±5%	8	100	1900	0.90	200
MH100533NJL□-□□□	33.0 ±5%	8	100	1600	1.00	200
MH100539NJL□-□□□	39.0 ±5%	8	100	1400	1.20	150
MH100547NJL□-□□□	47.0 ±5%	8	100	1200	1.30	150
MH100556NJL□-□□□	56.0 ±5%	8	100	1100	2.00	150
MH100568NJL□-□□□	68.0 ±5%	8	100	1000	2.20	100
MH100582NJL□-□□□	82.0 ±5%	8	100	900	2.50	100
MH1005R10JL□-□□□	100.0 ±5%	8	100	850	2.50	100

1). □ : Packaging Information... A : Bulk B : Taping Reel

2)."-□□□":Reference code

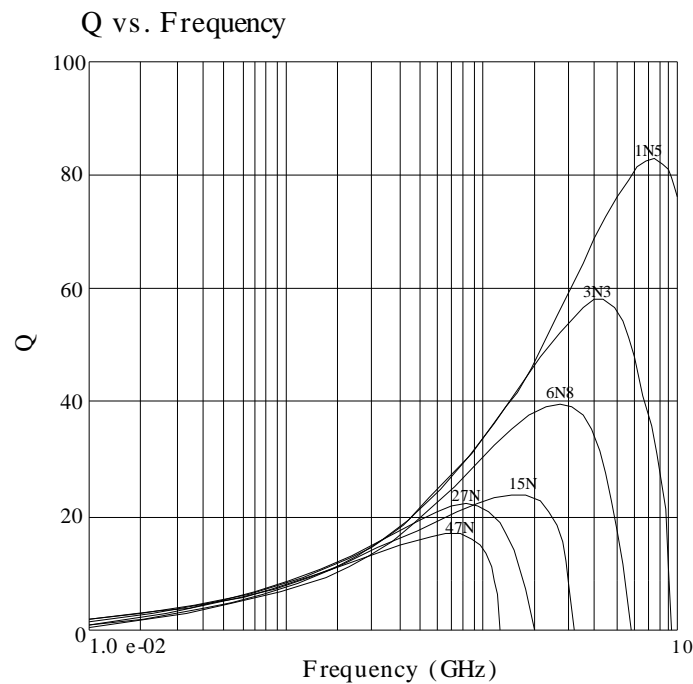
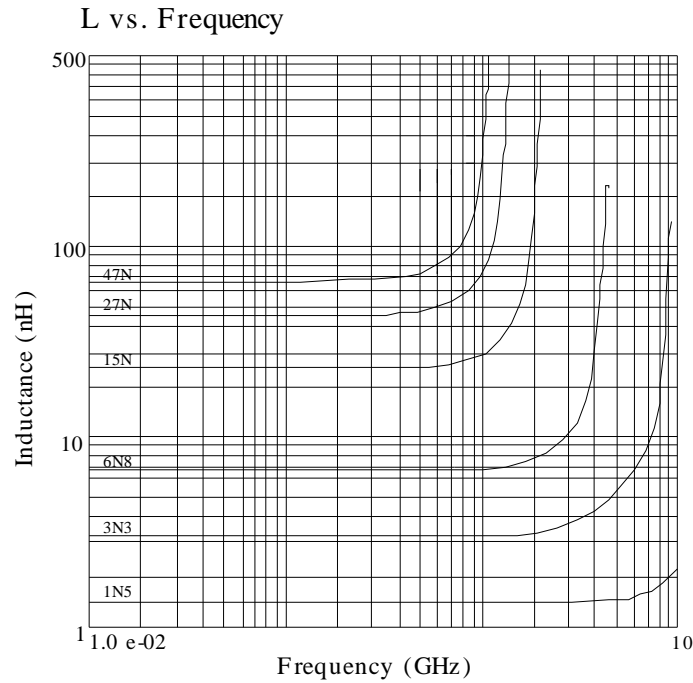
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VII . L / Q VS. FREQ. CURVE :



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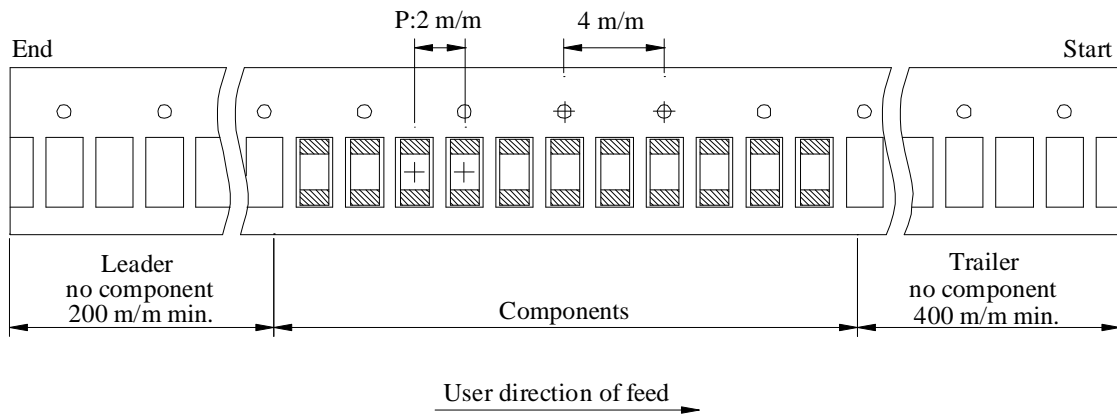
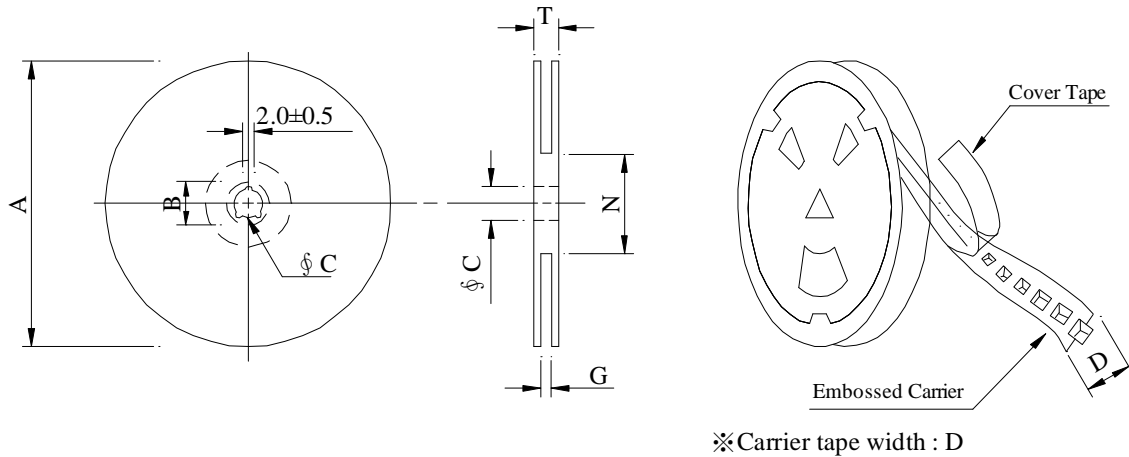
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VIII . PACKAGING INFORMATION :

(1) Configuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) QTY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY(kpcs)	G.W. (Kg)	Size (cm)
MH1005	10,000	60	07 - 08	500	5.5	42 x 41 x 24

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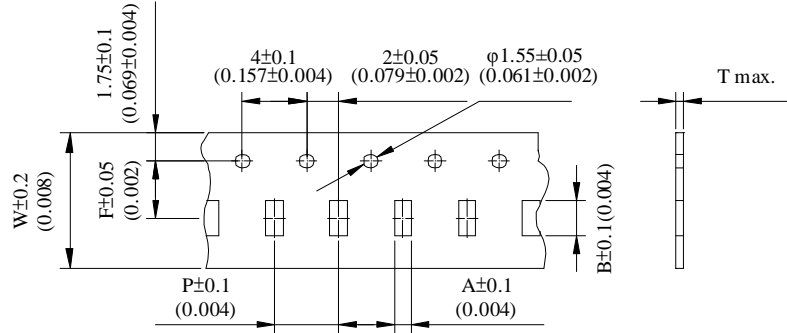
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(4) TYPE DIMENSIONS

Fig 1.



Unit:m/m

Type	A	B	F	P	T	W	Fig
MH1005	0.65	1.15	3.50	2.0	0.80	8.0	1

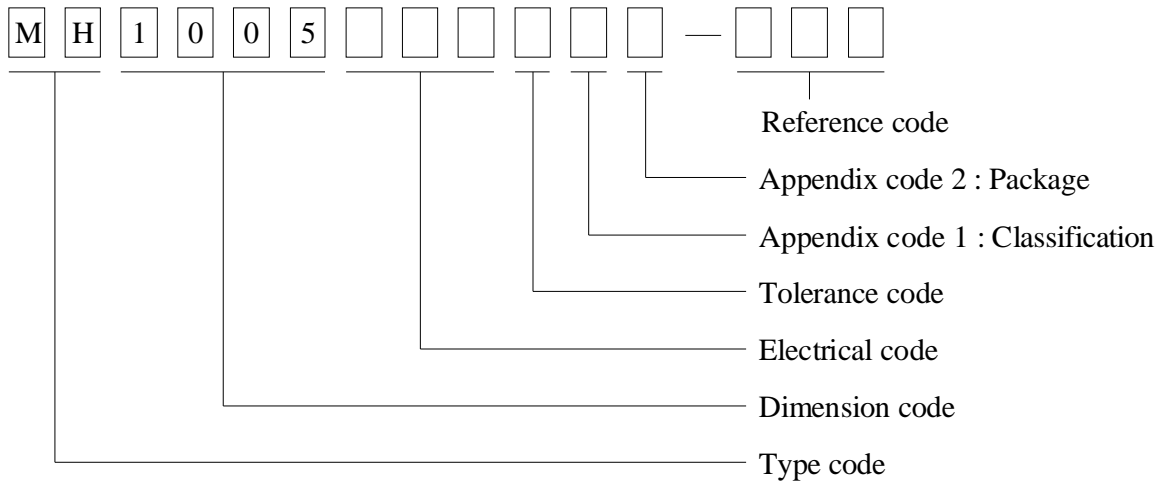
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IX . DWGING NUMBER EXPRESSION :



Appendix code 1 : Product Classification

L : Lead Free Standard products comply with RoHS' requirements

1 ~ 9 : Lead Free Special products comply with RoHS' requirements

Appendix code 2 : Package Information

Code	Inner package	Inner package QTY	Remark
A	T.B.D.	T.B.D.	
B	T / R (Reel package)	10,000 pcs	